

# 2SD1255

## Silicon NPN epitaxial planar type

For power switching

Complementary to 2SB932

### Features

- Low collector to emitter saturation voltage  $V_{CE(sat)}$
- Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- Large collector current  $I_C$
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ )

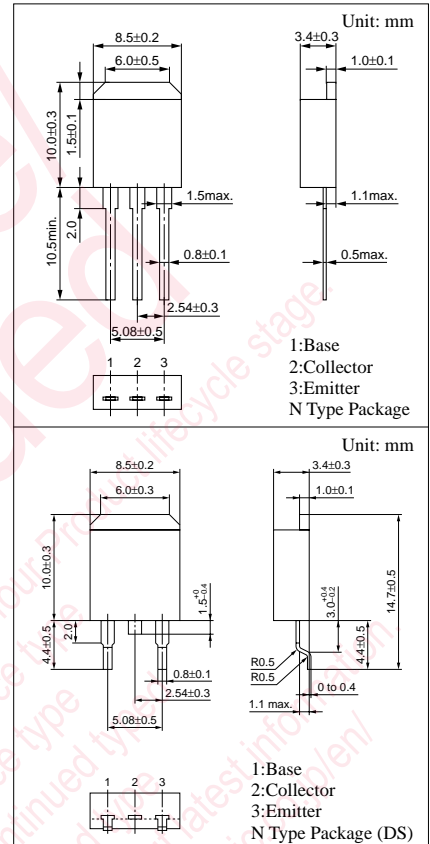
Parameter	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	130	V
Collector to emitter voltage	$V_{CEO}$	80	V
Emitter to base voltage	$V_{EBO}$	7	V
Peak collector current	$I_{CP}$	8	A
Collector current	$I_C$	4	A
Collector power dissipation	$P_C$	$T_C=25^\circ\text{C}$	35
		$T_a=25^\circ\text{C}$	1.3
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### Electrical Characteristics ( $T_C=25^\circ\text{C}$ )

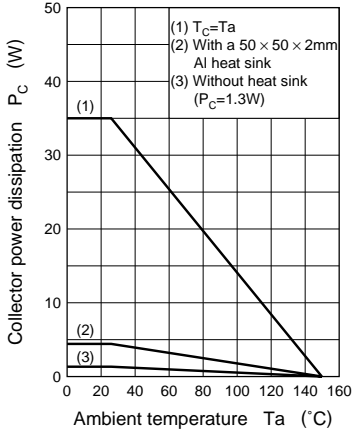
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 100\text{V}, I_E = 0$			10	$\mu\text{A}$
Emitter cutoff current	$I_{EBO}$	$V_{EB} = 5\text{V}, I_C = 0$			50	$\mu\text{A}$
Collector to emitter voltage	$V_{CEO}$	$I_C = 10\text{mA}, I_B = 0$	80			V
Forward current transfer ratio	$h_{FE1}$	$V_{CE} = 2\text{V}, I_C = 0.1\text{A}$	45			
	$h_{FE2}^*$	$V_{CE} = 2\text{V}, I_C = 1\text{A}$	60		260	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 3\text{A}, I_B = 0.15\text{A}$			0.5	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = 3\text{A}, I_B = 0.15\text{A}$			1.5	V
Transition frequency	$f_T$	$V_{CE} = 10\text{V}, I_C = 0.5\text{A}, f = 10\text{MHz}$		30		MHz
Turn-on time	$t_{on}$	$I_C = 1\text{A}, I_{B1} = 0.1\text{A}, I_{B2} = -0.1\text{A}, V_{CC} = 50\text{V}$		0.5		$\mu\text{s}$
Storage time	$t_{stg}$			2.5		$\mu\text{s}$
Fall time	$t_f$			0.15		$\mu\text{s}$

\* $h_{FE2}$  Rank classification

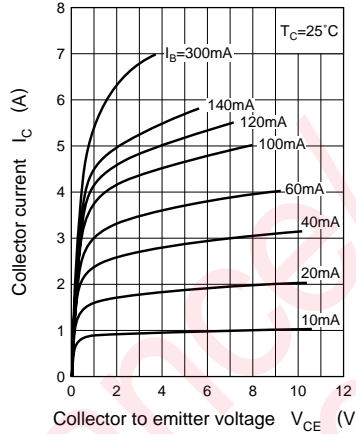
Rank	R	Q	P
$h_{FE2}$	60 to 120	90 to 180	130 to 260



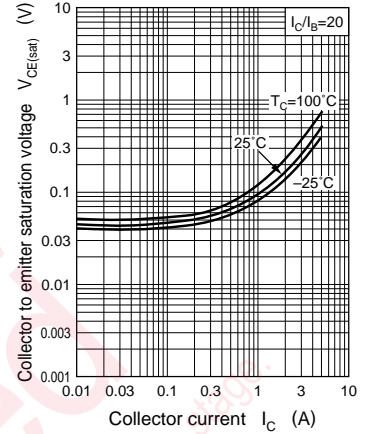
$P_C - T_a$



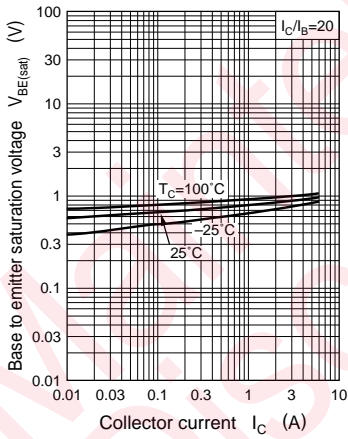
$I_C - V_{CE}$



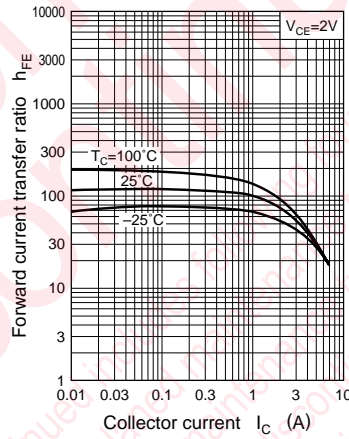
$V_{CE(sat)} - I_C$



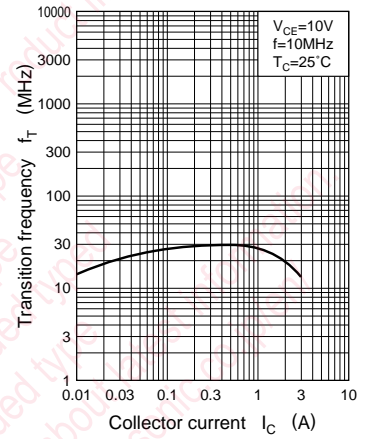
$V_{BE(sat)} - I_C$



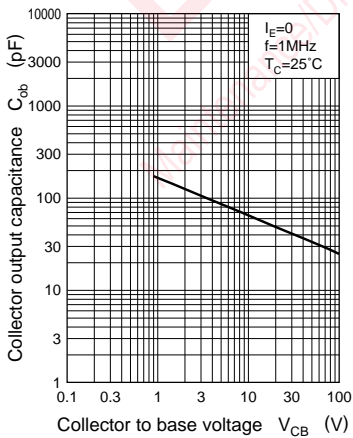
$h_{FE} - I_C$



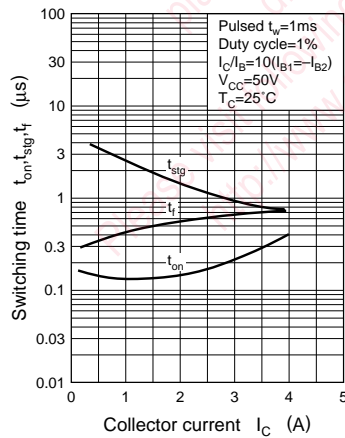
$f_T - I_C$



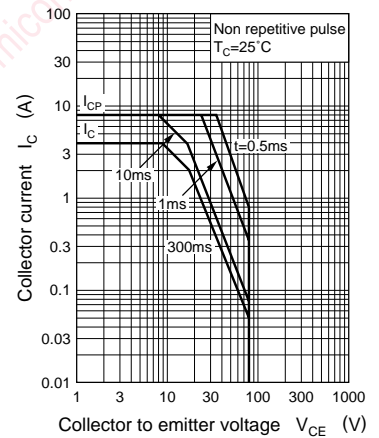
$C_{ob} - V_{CB}$

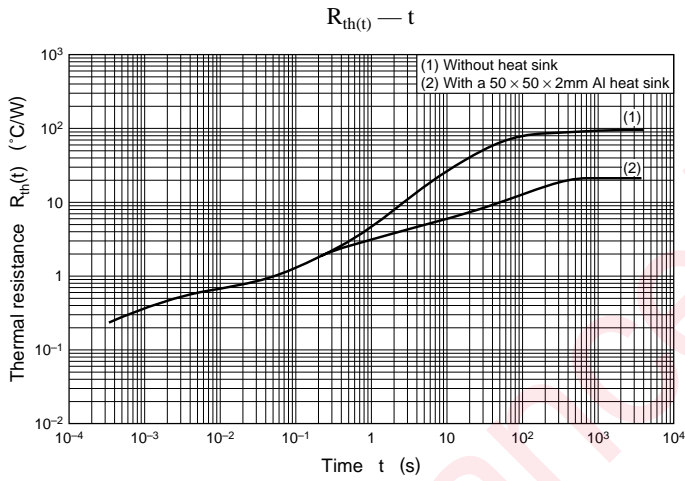


$t_{on}, t_{stg}, t_f - I_C$



Area of safe operation (ASO)





Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
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